



LAND



SEA



AIR



TEC300P



- Ampere® Altra®Q64-22 SoC, 64 cores, 2.2 GHz, Option Ampere Altra Q32 and Ampere Altra Max M128
- RAM DDR4-3200 MT/s Up to 4TB
- RTX MXM A4500 GPU (5888 CUDA)
- 2x10G(SFP), 2x1G, 3xUSB3.0, 1xVGA, 5xCOM
- DC-IN 18V~36V

Special Request:

- 2 x 10G SFP+
- AC Power In (Option)

Specifications

SYSTEM

CPU	Ampere® Altra® Q64-26 SoC, 64 cores, 2.2 GHz, 95W TDP Option Ampere Altra Q32 and Ampere Altra Max M128
Memory type	16 x DIMM sockets with individual memory channels Up to 4TB (16x 256 GB) DDR4 RDIMM memory, up to 3200 MT/s

GPU

Graphics Card	RTX MXM A4500 (5888 CUDA Cores)
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STORAGE

SSD	TBD
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ETHERNET

Ethernet	2 x 1 Gigabit Ethernet with RJ45 2 x 10G SFP+
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SIDE I/O

RJ45 GLAN	2
10 GbE SFP+	2
COM	5
USB3.0	3
VGA	1
DC-IN	1
Power Button	1 x Power Button with LED backlight

OS SUPPORT LIST

OS	Linux RedHat ,Ubuntu
Power Requirement	28V DC-IN (18V-36V)
Dimension	TBD
Weight	10 KG
Operating Temp.	0°C to 60°C
Storage Temp.	-40°C to 85°C
Relative Humidity	5% to 95%, non-condensing

ENVIRONMENTAL

MIL-STD-810 Test	<p>Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)</p> <p>Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)</p> <p>Method 501.5, Procedure I (Storage/High Temperature)</p> <p>Method 501.5, Procedure II (Operation/High Temperature)</p> <p>Method 502.5, Procedure I (Storage/Low Temperature)</p> <p>Method 502.5, Procedure II (Operation/Low Temperature)</p> <p>Method 503.5, Procedure I (Temperature shock)</p> <p>Method 507.5, Procedure II (Temperature & Humidity)</p> <p>Method 509.7 Salt Spray (50±5)g/L</p> <p>Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration)</p> <p>Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration)</p> <p>Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock)</p> <p>Method 516.6, Shock-Procedure I Operating (Mechanical Shock)</p>
Reliability	<p>Conduction Cooling.</p> <p>Designed & Manufactured using ISO 9001 Certified Quality Program.</p>
EMC	<p>EN 61000-4-2: Air discharge: 8 kV, Contact discharge: 6kV</p> <p>EN 61000-4-3: 10V/m</p> <p>EN 61000-4-4: Signal and DC-Net: 1 kV</p> <p>EN 61000-4-5: Leads vs. ground potential 1kV, Signal und DC-Net: 0.5 kV</p>

Ordering Information

	TEC300P	
CPU	Ampere Q64-22	Ampere Q64-22
GPU	MXM RTXA2000	MXM RTXA4500
RAM	Up to DDR4-1.5TB	
USB3.0	4	
VGA	1	
DP	4	
CAN BUS	2	
COM	1	
GLAN	2	
10G SFP+ LAN	2	
Power	DC 18V~36V	

Appearance



Dimension

